

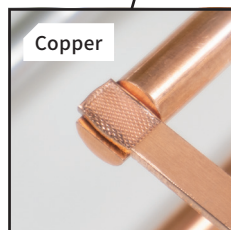
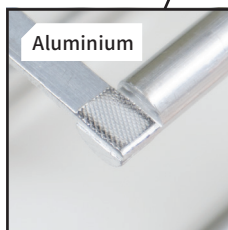


Application

Bonding

Busbar and Rod Bonding

Aluminium/Copper



Al/Cu Bar : W = 7.0 mm; t = 2.0 mm
Al/Cu Rod : D = Ø8 mm

Key Points

- ✓ Round parts bonded reliably without energy loss
- ✓ No adhesives required
- ✓ Bonding at room-temperature and under atmospheric conditions
- ✓ Ingot bonding
- ✓ No discoloration or damage to parts
- ✓ Minimal anvil and tool heating

System Used

- ✓ 15MZs



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